Product Change Notification: MFOL-02XEMI584

Date:

07-Sep-2026

Product Category:

Ethernet Controllers

Notification Subject:

CCB 8503 Final Notice: Qualification of MMT as an additional assembly site for LAN9420-NU and LAN9420I-NU catalog part numbers (CPN) available in 128L TQFP (14x14x1mm) package.

Affected CPNs:

MFOL-02XEMI584_Affected_CPN_09072026.pdf
MFOL-02XEMI584_Affected_CPN_09072026.csv

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of MMT as an additional assembly site for LAN9420-NU and LAN9420I-NU catalog part numbers (CPN) available in 128L TQFP (14x14x1mm) package.

Pre and Post Summary Changes:

	Pre Change		**Post Change**			**Change (Yes/No)**
Assembly Site	ASE Inc. (ASE)		ASE Inc. (ASE)		Microchip Technology Thailand (Branch) (MMT)	Yes
Wire Material	Au	PdCu	Au	PdCu	Au	Yes

Die Attach Material	1076WA (PFAS-free)	1076WA (PFAS-free)	QMI519 (PFAS-free)	Yes
Molding Compound Material	G631H	G631H	G700HA	Yes
Lead-Frame Material	C7025	C7025	C7025	No
Lead-Frame Design	See 'Pre and Post Change Summary' attachment for comparison.			No

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve on-time delivery performance and manufacturability by qualifying MMT as an additional assembly site.

Change Implementation Status: In Progress

Estimated First Ship Date: 29 October 2026 (date code: 2644)

Note Below EFSD: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	September 2026					**October 2026**			
Work Week	36	37	38	39	40	41	42	43	44
Qual Report Availability		X							
Final PCN Issue Date		X							
Estimated Implementation Date									X

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.
Note: This is a qualification by similarity (QBS) to CCB# 7084 and CCB# 7864.

Revision History: September 07, 2026: Issued final notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_MFOL-02XEMI584_Pre and Post Change Summary.pdf
PCN_MFOL-02XEMI584_Qualification Report_CCB7084.pdf
PCN_MFOL-02XEMI584_Qualification_Report_CCB7864.pdf

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our **PCN home page** select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the **PCN FAQ** section.

If you wish to change your PCN profile, including opt out, please go to the **PCN home page** select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

MFOL-02XEMI584 - CCB 8503 Final Notice: Qualification of MMT as an additional assembly site for LAN9420-NU and LAN9420I-NU catalog part numbers (CPN) available in 128L TQFP (14x14x1mm) package.

Affected Catalog Part Numbers (CPN):

LAN9420-NU

LAN9420I-NU

CCB 8503
Pre and Post Change Summary
PCN #: MFOL-02XEMI584

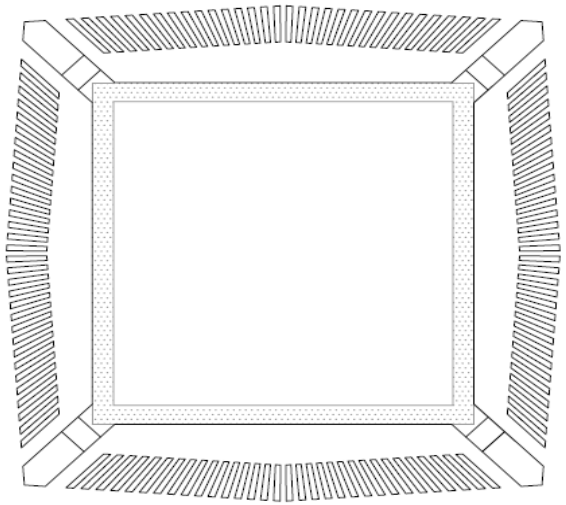


A Leading Provider of Smart, Connected and Secure Embedded Control Solutions



Lead Frame Comparison

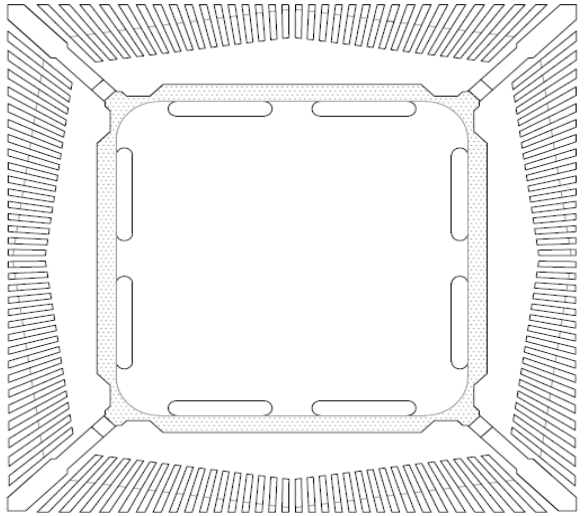
ASE



Note: Not to scale

Lead-Frame Material	C7025

MMT



Note: Not to scale

Lead-Frame Material	C7025



Qualification Report Summary

RELIABILITY LABORATORY

PCN #: MFOL-02XEMI584

Date:

November 11, 2024

Qualification of MMT as an additional assembly site for LAN9420-NU and LAN9420I-NU catalog part numbers (CPN) available in 128L TQFP (14x14x1mm) package.

PACKAGE QUALIFICATION REPORT

Purpose:

Qualification of MMT as an additional assembly site for LAN9420-NU and LAN9420I-NU catalog part numbers (CPN) available in 128L TQFP (14x14x1mm) package.

CN:	E000241334
QUAL ID:	R2401146
QUAL ID Rev.:	A
MP CODE:	TDAA19E5XEA8
Part No.:	PIC32MX795F512L-80V/PF
Bonding No.:	BD-002486 Rev. 01
CCB No.:	7084 and 8503

Lead Frame

Paddle Size:	280 x 280 mils
Material:	C7025
DAP Surface Prep:	Bare Cu
Process:	Stamped
Lead Lock:	No
Part Number:	10110015
Lead Plating:	Matte Sn
Treatment:	None

Bond Wire

Wire:	Au wire

Die Attach Material

Epoxy:	3280

Mold Compound

Mold Compound:	G700HA

Package

Type:	100L TQFP
Package Size:	14 x 14 x 1.0 mm

Manufacturing Information

Assembly Lot No.	Wafer Lot No.	Date Code
MMT-252001357.000	TC11925092721.120	24334WC
MMT-252001358.000	TC11925092721.120	24334WD
MMT-252001359.000	TC11925092721.120	24334WG

Result: **Pass**

Conclusion:

100L TQFP (14x14x1.0 mm) assembled by MMT pass reliability test per QCI-39000. This package was qualified the Moisture/Reflow Sensitivity Classification Level 1 at 260°C reflow temperature per IPC/JEDEC J-STD-020E standard.

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
	Electrical Test: +25°C and 105°C **System:** J750	JESD22-A113	693(0)	0/693		Good Devices
	Bake 150°C, 24 hrs. **System:** CHINEE	JIP/IPC/JEDEC J-STD-020E		693		
Precondition Prior Perform Reliability Tests (At MSL Level 1)	85°C/85%RH Moisture Soak 168 hrs. **System:** TABAI ESPEC Model PR-3SPH			693		
	3x Convection-Reflow 265°C max **System:** Vitronics Soltec MR1243			693		
	Electrical Test: +25°C and 105°C **System:** J750		693(0)	0/693	Pass	
Temp Cycle	**Stress Condition:** -65°C to +150°C, 500 Cycles **System:** TABAI ESPEC TSA-70H	JESD22-A104		0/231	Pass	Parts had been pre-conditioned at 260°C
	Electrical Test: +105°C **System:** J750		231(0)	0/231	Pass	77 units / lot
	Bond Strength: Wire Pull (>2.50 grams)		15(0)	0/15	Pass	
UNBIASED-HAST	**Stress Condition:** +130°C/85%RH, 96 hrs. **System:** HAST 6000X	JESD22-A118		0/231	Pass	Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C **System:** J750		231(0)	0/231	Pass	77 units / lot
HAST	**Stress Condition:** +130°C/85%RH, 96 hrs. **Bias Volt:** VDD=3.3 Volts **System:** HAST 6000X	JESD22-A110		0/231	Pass	Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C and 105°C **System:** J750		231(0)	0/231	Pass	77 units / lot

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
High Temperature Storage Life	**Stress Condition:** Bake 175°C, 504 hrs. **System:** TPS Bake Oven	JESD22-A103		0/45	Pass	45 units
	Electrical Test: +25°C and 105°C **System:** J750		45(0)	0/45	Pass	
	Steam Aging: Temp 93°C,8Hrs **System:** SAS-3000	J-STD-002	22(0)	0/22	Pass	
Solderability Temp 215°C	**Solder Dipping:** Solder Temp.215°C **Solder material:** SnPb Sn63, Pb37 **System:** ERSA RA 2200D			0/22		
	Visual Inspection: External Visual Inspection			0/22	Pass	
	Steam Aging: Temp 93°C,8Hrs **System:** SAS-3000	J-STD-002	22(0)	0/22	Pass	
Solderability Temp 245°C	**Solder Dipping:**Solder Temp.245°C **Solder material:**Pb Free Sn 95.5Ag3.9 Cu0.6 **System:** ERSA RA 2200D			0/22		
	Visual Inspection: External Visual Inspection			0/22	Pass	
Bond Strength Data Assembly	Wire Pull (>2.50 grams)	Mil. Std. 883-2011	30(0)	0/30	Pass	
	Bond Shear (>15.00 grams)	CDF-AEC-Q100-001	30(0)	0/30	Pass	



Qualification Report Summary

RELIABILITY LABORATORY

PCN #: MFOL-02XEMI584

Date:

January 8, 2026

Qualification of MMT as an additional assembly site for LAN9420-NU and LAN9420I-NU catalog part numbers (CPN) available in 128L TQFP (14x14x1mm) package.

PACKAGE QUALIFICATION REPORT

Purpose:

Qualification of MMT as an additional assembly site for LAN9420-NU and LAN9420I-NU catalog part numbers (CPN) available in 128L TQFP (14x14x1mm) package.

CN:	E000287632
QUAL ID:	R2501341
QUAL ID Rev.:	A
MP CODE:	UG0241E5X04A
Part No.:	A42MX16-VQG100-B4
Bonding No.:	BD-003783 Rev.01
CCB No.:	7864 and 8503

Lead Frame

Paddle Size:	315 x 315 mils
Material:	C7025
DAP Surface Prep:	Ag Ring Plated
Process:	Etched
Lead Lock:	No
Part Number:	10110019
Lead Plating:	Matte Tin

Bond Wire

Wire:	Au wire

Die Attach Material

Epoxy:	QMI519

Mold Compound

Mold Compound:	G700HA

Package

Type:	100L TQFP
Package Size:	14 x 14mm

Manufacturing Information

Assembly Lot No.	Wafer Lot No.	Date Code
MMT-262700747.000	GF02923303599.110	254082R
MMT-262800222.000	GF02923303599.120	254182S
MMT-262800223.000	GF02923303599.100	254182T

Result: **Pass**

Conclusion:

100L TQFP (14x14 mm) assembled by MMT pass reliability test per QCI-39000. This package was qualified the Moisture/Reflow Sensitivity Classification Level 3 at 260°C reflow temperature per IPC/JEDEC J-STD-020E standard.

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
	Electrical Test: +25°C and 85°C **System:** J750	JESD22-A113	693(0)	0/693	Pass	Good Devices
	Bake 150°C, 24 hrs. **System:** CHINEE	JIP/IPC/JEDEC J-STD-020E		693		
Precondition Prior Perform Reliability Tests (At MSL Level 3)	30°C/60%RH Moisture Soak 192 hrs. **System:** TABAI ESPEC Model PR-3SPH	JIP/IPC/JEDEC J-STD-020E		693		
	3x Convection-Reflow 265°C max **System:** Vitronics Soltec MR1243	JIP/IPC/JEDEC J-STD-020E		693		
	Electrical Test: +25°C and 85°C **System:** J750		693(0)	0/693	Pass	
	Stress Condition: -65°C to +150°C, 500 Cycles **System:** TABAI ESPEC TSA-70H	JESD22-A104		231		Parts had been pre-conditioned at 260°C
Temp Cycle	**Electrical Test:** +85°C **System:** J750		231(0)	0/231	Pass	77 units / lot
	Bond Strength: Wire Pull (>4.00 grams)		15(0)	0/15	Pass	
	Stress Condition: +130°C/85%RH, 96 hrs. **System:** HAST 6000X	JESD22-A118		231		Parts had been pre-conditioned at 260°C
UNBIASED-HAST	**Electrical Test:** +25°C **System:** J750		231(0)	0/231	Pass	77 units / lot
	Stress Condition: +130°C/85%RH, 192 hrs. **System:** HAST 6000X			231		
	Electrical Test: +25°C **System:** J750		231(0)	0/231	Pass	77 units / lot

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
High Temperature Storage Life	**Stress Condition:** Bake 175°C, 504 hrs. **System:** TPS Bake Oven	JESD22-A103		45		45 units
	Electrical Test: +25°C and 85°C **System:** J750		45(0)	0/45	Pass	
Solderability Temp 215°C	**Steam Aging:** Temp 93°C, 8Hrs **System:** SAS-3000	J-STD-002		22		
	Solder Dipping: Solder Temp 215°C **Solder material:** SnPb Sn63, Pb37 **System:** ERSA RA 2200D			22		
	Visual Inspection: External Visual Inspection		22(0)	0/22	Pass	
Solderability Temp 245°C	**Steam Aging:** Temp 93°C, 8Hrs **System:** SAS-3000	J-STD-002		22		
	Solder Dipping: Solder Temp.245°C **Solder material:** Pb Free Sn 95.5Ag3.9 Cu0.6 **System:** ERSA RA 2200D			22		
	Visual Inspection: External Visual Inspection		22(0)	0/22	Pass	
Wire sweep	Wire sweep Inspection 15 Wires / lot	-	45(0) Wires	0/45	Pass	
Physical Dimensions	Physical Dimension, 10 units / 1 lot	JESD22-B100 /B108	30(0) Units	0/30	Pass	
Bond Strength Data Assembly	Wire Pull (>4.00 grams)	Mil. Std. 883-2011	30(0) Wires	0/30	Pass	
	Bond Shear (>18.00 grams)	CDF-AEC-Q100-001	30(0) Bonds	0/30	Pass	